

APTBD3216SURKSYKC-01

3.2 x 1.6 mm SMD Chip LED Lamp



DESCRIPTIONS

- The Hyper Red source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode
- The Super Bright Yellow device is made with AlGaInP (on GaAs substrate) light emitting diode chip
- · Electrostatic discharge and power surge could damage the LEDs
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- · All devices, equipments and machineries must be electrically grounded

FEATURES

- 3.2 mm x 1.6 mm SMD LED, 1.8 mm thickness
- · Low power consumption
- · Ideal for backlight and indicator
- Package: 2000 pcs / reel
- Moisture sensitivity level: 3
- · RoHS compliant

APPLICATIONS

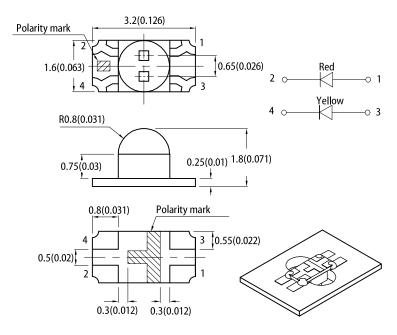
- Backlight
- Status indicator
- Home and smart appliances
- · Wearable and portable devices
- · Healthcare applications

ATTENTION

Observe precautions for handling electrostatic discharge sensitive devices

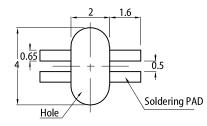


PACKAGE DIMENSIONS



RECOMMENDED SOLDERING PATTERN

(units: mm; tolerance: \pm 0.1)



- 1. All dimensions are in millimeters (inches)
- Tolerance is ±0.2(0.008") unless otherwise noted.
 The specifications, characteristics and technical data described in the datasheet are subject to
- change without prior notice.

 The device has a single mounting surface. The device must be mounted according to the specifications.

SELECTION GUIDE

Part Number	Emitting Color (Material)	Lens Type	Iv (mcd) @ 20mA [2]		Viewing Angle [1]
			Min.	Тур.	201/2
APTBD3216SURKSYKC-01	■ Hyper Red (AlGalnP)	- Water Clear	700	1500	30°
			*300	*600	
	Super Bright Yellow (AlGalnP)		200	450	
			*200	*450	

1. 91/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value
2. Luminous intensity / luminous flux: +/-15%.
** Luminous intensity / luminous flux: -/-15%.

Luminous intensity value is traceable to CIE127-2007 standards.





ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Symbol	Emitting Color	Value		Unit
			Тур.	Max.	
Wavelength at Peak Emission I _F = 20mA	λ_{peak}	Hyper Red Super Bright Yellow	645 590	-	nm
Dominant Wavelength I _F = 20mA	λ _{dom} ^[1]	Hyper Red Super Bright Yellow	630 590	-	nm
Spectral Bandwidth at 50% Φ REL MAX I _F = 20mA	Δλ	Hyper Red Super Bright Yellow	28 20	-	nm
Capacitance	С	Hyper Red Super Bright Yellow	35 20	-	pF
Forward Voltage I _F = 20mA	V _F ^[2]	Hyper Red Super Bright Yellow	1.95 2	2.5 2.5	V
Reverse Current (V _R = 5V)	I _R	Hyper Red Super Bright Yellow	-	10 10	μА

1. The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd:±1nm.)
2. Forward voltage: ±0.1V.
3. Wavelength value is traceable to CIE127-2007 standards.
4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

ABSOLUTE MAXIMUM RATINGS at $T_A=25$ °C

Parameter	Symbol	Value	Unit		
	-	Hyper Red	Super Bright Yellow		
Power Dissipation	P _D	75	75	mW	
Reverse Voltage	V _R	5	5	V	
Junction Temperature	TJ	115	115	°C	
Operating Temperature	T _{op}	-40 To +85		°C	
Storage Temperature	T _{stg}	-40 To +85		°C	
DC Forward Current	I _F	30	30	mA	
Peak Forward Current	I _{FM} ^[1]	185	175	mA	
Electrostatic Discharge Threshold (HBM)	-	3000	3000	V	

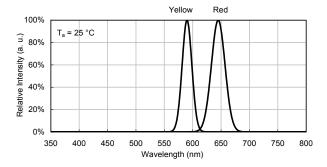
Notes:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.



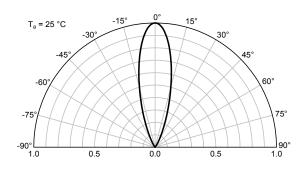


TECHNICAL DATA

RELATIVE INTENSITY vs. WAVELENGTH



SPATIAL DISTRIBUTION



HYPER RED Forward Current vs. Luminous Intensity vs. Forward Voltage **Forward Current** 50 2.5 Luminous intensity normalised at T_a = 25 °C T_a = 25 °C 2.0 Forward current (mA) 1.5 20 mA 20 1.0 10 0.5 0.0

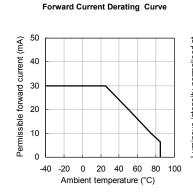
0 10 20 30 40 50

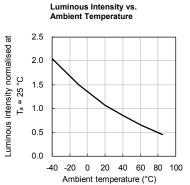
Forward current (mA)

2.5

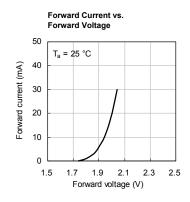
2.1 2.3

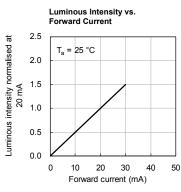
Forward voltage (V)

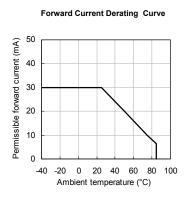


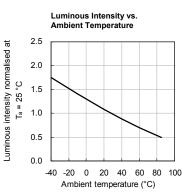


SUPER BRIGHT YELLOW









1.5 1.7 1.9

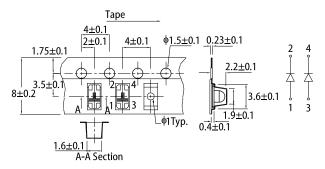


REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS

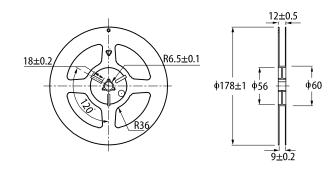
300 above 255°C (°C) 260°C max. 30s max. 10s max. 250 3°C/s max. 6°C/s max. 200 150 Temperature pre-heating 100 150~200°C above 217°C 60~120s 60~150s 50 -25°C 0 0 50 100 150 200 250 300 (sec) Time

- 1. Don't cause stress to the LEDs while it is exposed to high temperature.
 2. The maximum number of reflow soldering passes is 2 times.
 3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

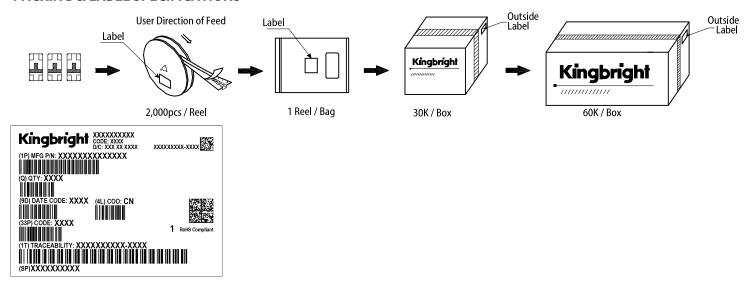
TAPE SPECIFICATIONS (units:mm)



REEL DIMENSION (units: mm)



PACKING & LABEL SPECIFICATIONS



PRECAUTIONARY NOTES

- The information included in this document reflects representative usage scenarios and is intended for technical reference only.
- The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.

 The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening
- liabilities, such as automotive or medical usage, please consult with Kingbright representative for further assistance. The contents and information of this document may not be reproduced or re-transmitted without permission by Kingbright. All design applications should refer to Kingbright application notes available at https://www.KingbrightUSA.com/Application

